

# N-CHANNEL ENHANCEMENT MODE MOSFET PLUS NPN TRANSISTOR

**Features** 

- N-Channel MOSFET and NPN Transistor in One Package
- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 2)
- ESD Protected MOSFET Gate up to 2kV
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

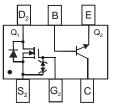
- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Alloy 42 Lead frame. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 5
- Ordering Information: See Page 5
- Weight: 0.006 grams (approximate)





SOT-363

TOP VIEW



TOP VIEW Internal Schematic

#### Maximum Ratings – MOSFET, Q1 @T<sub>A</sub> = 25°C unless otherwise specified

Characteris	stic	Symbol	Value	Units
Drain-Source Voltage		V <sub>DSS</sub>	50	V
Gate-Source Voltage		V <sub>GSS</sub>	±12	V
Drain Current (Note 1)	Continuous	Ι <sub>D</sub>	160	mA
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	560	mA

#### Maximum Ratings - NPN Transistor, Q2 @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	50	V
Collector-Emitter Voltage	V <sub>CEO</sub>	45	V
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V
Collector Current	lc	100	mA

#### Thermal Characteristics, Total Device @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 1)	PD	250	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ ext{ heta}JA}$	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes: 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

2. No purposefully added lead. Halogen and Antimony Free.

3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.



# Electrical Characteristics - MOSFET @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 2)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	50	_	_	V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	10	μΑ	$V_{DS} = 50V, V_{GS} = 0V$
Gate-Body Leakage	I <sub>GSS</sub>	_	_	1.0 5.0	μA	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$ $V_{GS} = \pm 12V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.7	0.8	1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$
Static Drain-Source On-Resistance	Descent	_	3.1	4	Ω	$V_{GS} = 4V, I_D = 100mA$
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>	_	4	5	52	$V_{GS} = 2.5V, I_D = 80mA$
Forward Transconductance	<b>g</b> fs	180	—	—	mS	$V_{DS} = 10V, I_D = 100mA, f = 1.0KHz$
DYNAMIC CHARACTERISTICS						
Input Capacitance	Ciss	_	25		pF	
Output Capacitance	C <sub>oss</sub>	_	5	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ = f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	2.1		pF	

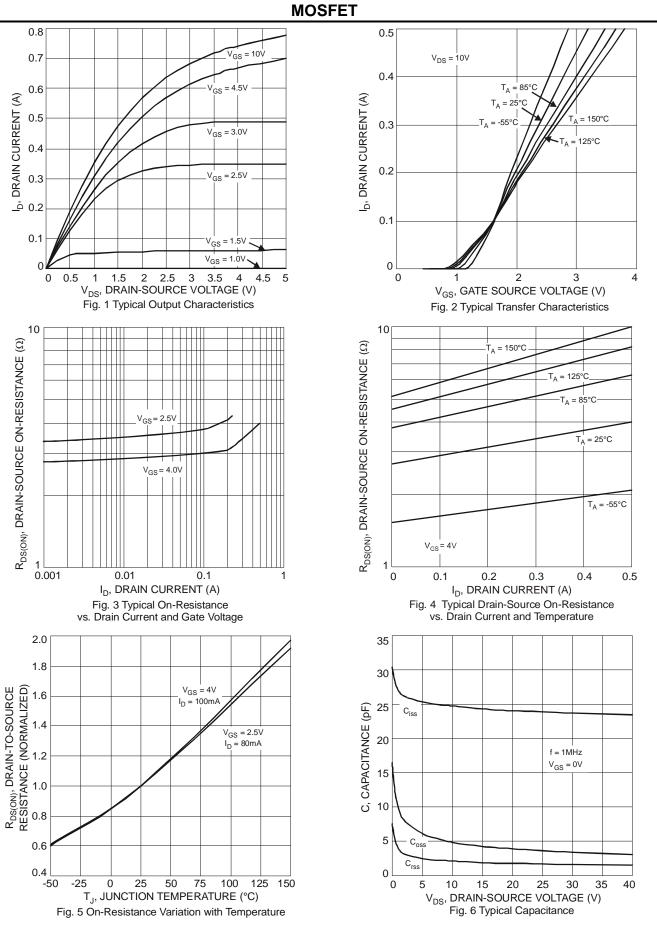
## Electrical Characteristics - NPN Transistor @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	(Note 4)	V <sub>(BR)CBO</sub>	50	_	—	V	$I_{C} = 10\mu A, I_{B} = 0$
Collector-Emitter Breakdown Voltage	(Note 4)	V <sub>(BR)CEO</sub>	45	_	_	V	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	(Note 4)	V <sub>(BR)EBO</sub>	6	_	_	V	$I_{E} = 1 \mu A, I_{C} = 0$
DC Current Gain	(Note 4)	h <sub>FE</sub>	200	290	450	_	$V_{CE} = 5.0V, I_{C} = 2.0mA$
Collector-Emitter Saturation Voltage	(Note 4)	V <sub>CE(SAT)</sub>		—	100 300	mV	$I_{C} = 10$ mA, $I_{B} = 0.5$ mA $I_{C} = 100$ mA, $I_{B} = 5.0$ mA
Base-Emitter Saturation Voltage	(Note 4)	V <sub>BE(SAT)</sub>		700 900	—	mV	$I_{C} = 10mA$ , $I_{B} = 0.5mA$ $I_{C} = 100mA$ , $I_{B} = 5.0mA$
Base-Emitter Voltage	(Note 4)	V <sub>BE</sub>	580 —	660 —	700 770	mV	$V_{CE} = 5.0V, I_C = 2.0mA$ $V_{CE} = 5.0V, I_C = 10mA$
Collector Cut-Off Current	(Note 4)	I <sub>CBO</sub>		_	15 5.0	nA μA	V <sub>CB</sub> = 30V V <sub>CB</sub> = 30V, T <sub>A</sub> = 150°C
Collector-Emitter Cut-Off Current	(Note 4)	ICES	_	_	100	nA	$V_{CE} = 45V$
Gain Bandwidth Product		f⊤	100	—	—	MHz	$V_{CE} = 5.0V, I_C = 10mA, f = 100MHz$
Output Capacitance		C <sub>OBO</sub>		—	4.5	pF	V <sub>CB</sub> = 10V, f = 1.0MHz
Noise Figure		NF	_	_	10	dB	$V_{CE} = 5V$ , $R_S = 2.0k\Omega$ , f = 1.0kHz, BW = 200Hz

Notes: 4. Short duration pulse test used to minimize self-heating effect.



#### DMB53D0UDW

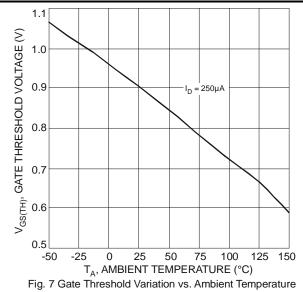


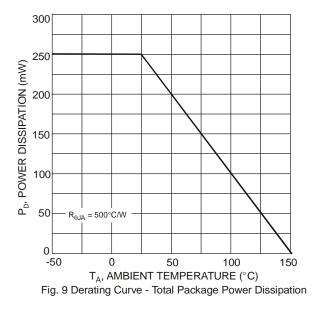
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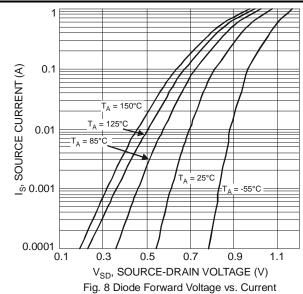


#### DMB53D0UDW

## **MOSFET (continued)**









#### DMB53D0UDW

 $T_A = -50^{\circ}C$ 

1,000

25°C Τ<sub>A</sub>

1 10 100 I<sub>C</sub>, COLLECTOR CURRENT (mA)

Fig. 11 Typical Collector-Emitter Saturation Voltage vs. Collector Current

 $T_A = 150^{\circ}C$ 

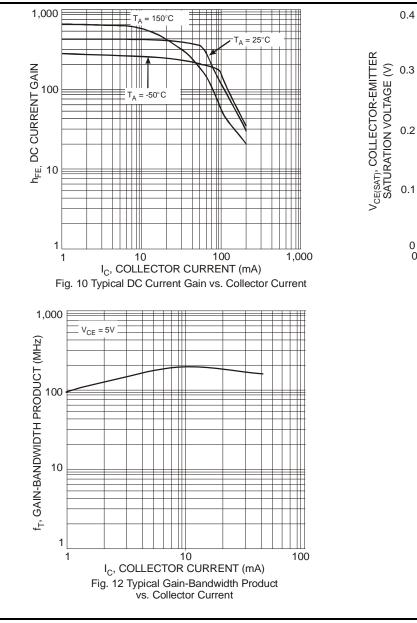
#### **NPN Transistor**

0.4

0

0.1

 $\frac{I_{C}}{I_{B}} = 20$ 



#### Ordering Information (Note 5)

Part Number	Case	Packaging
DMB53D0UDW-7	SOT-363	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

#### **Marking Information**

Date Code Key			•	<u>М</u> В1	M M M	YM = Da Y = Yea	Marking Co ate Code M r (ex: V = 2 hth (ex: 9 =	larking 2008)	ber)			
Year	2008		2009	2010		2011	2012		2013	2014		2015
Code	V		W	Х		Y	Z		А	В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

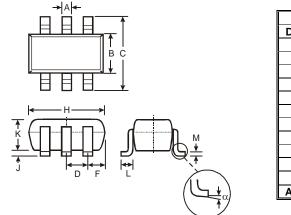
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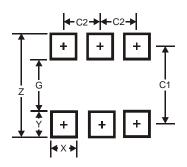


#### **Package Outline Dimensions**



	SOT-363							
Dim	Min	Max						
Α	0.10	0.30						
в	1.15	1.35						
С	2.00	2.20						
D	0.65 Typ							
F	0.40	0.45						
Н	1.80	2.20						
J	0	0.10						
Κ	0.90 1.00							
L	0.25	0.40						
М	0.10	0.22						
α	0°	8°						
All Di	mensions	in mm						

## Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



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